

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A method, comprising:
applying thermoplastic bonder to the perimeter ~~determining parameters of a ball~~
grid array (BGA) package; ~~having~~
applying the thermoplastic bonder to an array of solder balls, included in the BGA
package, independent of the applying of the thermoplastic bonder to the
perimeter of the BGA package; and
attaching a printable circuit board (PCB) to the BGA package via the
thermoplastic bonder on the perimeter of the BGA package and the array
of solder balls with the thermoplastic bonder~~and applying a bonder to the~~
~~parameters of the BGA package, wherein the bonder is applied~~
~~independently of the array of solder balls, and the bonder is applied~~
~~surrounding the array of solder balls.~~
2. (Currently Amended) The method of claim 1, wherein the BGA package comprises:
an integrated circuit (IC) device;
a first surface coupled with the IC device; and
~~a printed circuit board (PCB) having a second surface, the second surface aligned~~
~~with the first surface using the array of solder balls, wherein the array of~~
~~solder balls placed in between the first surface and the second surface; and~~
solder joints to attach the array of solder balls with the first surface and the a
second surface.

3. (Currently Amended) The method of claim 1, wherein the applying of the thermoplastic bonder comprises applying the bonder between the first surface and the second surface to provide resistance to the BGA package against warpage.
4. (Previously Presented) The method of claim 3, wherein the warpage comprises at least one of opening, cracking, curving, bending, and breaking of the second surface.
5. (Currently Amended) The method of claim 1, wherein the thermoplastic bonder is further applied to one or more of edges and corners of the BGA package.
6. (Currently Amended) The method of claim 1, wherein the applying of the thermoplastic bonder comprises applying the thermoplastic bonder using a bonder dispenser.
7. (Cancelled)
8. (Currently Amended) The method of claim 1, wherein the applying of the thermoplastic bonder comprises ~~applying the thermoplastic bonder~~ using a hot melting jig or a dispenser, the hot melting jig and the dispenser comprise at least one of a hot melt hand applicator and an adhesive unit.
9. (Cancelled)
10. (Currently Amended) The method of claim 1, wherein the independent application of the thermoplastic bonder is performed using software to control placement distance of the thermoplastic bonder with respect to the array of solder balls.
- 11-31 (Cancelled)